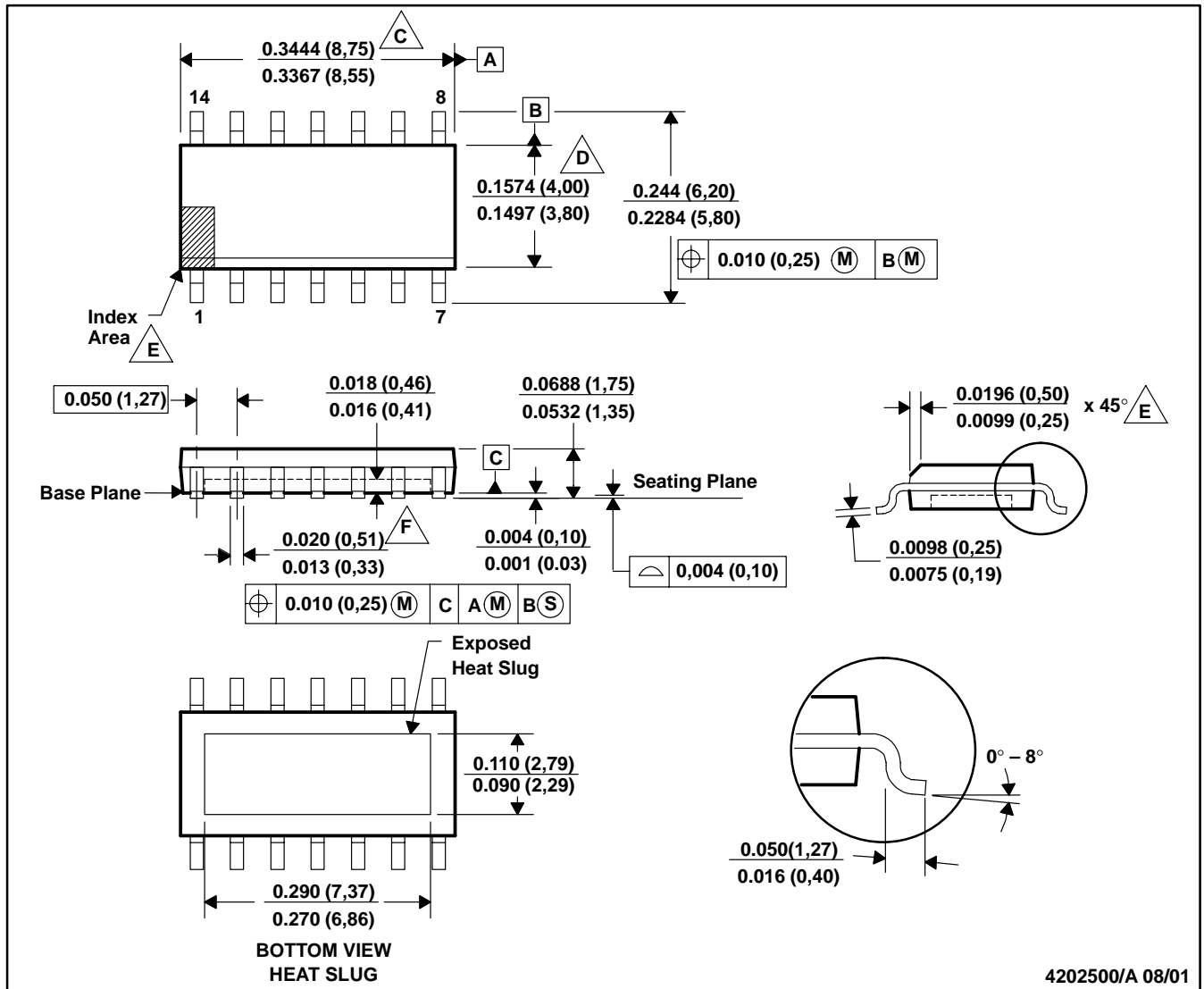


DTH (R-PDSO-G14)

PLASTIC SMALL-OUTLINE



4202500/A 08/01

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body length dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions and gate burrs shall not exceed 0.006 (0,15) per side.  
 D. Body width dimension does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 0.010 (0,25) per side.  
 E. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the cross-hatched area.  
 F. The lead width, as measured 0.014 (0,36) or greater above the seating plane, shall not exceed a maximum value of 0.024 (0,61).  
 G. Falls within JEDEC MS-012-AB.

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